

METHOD FOR FABRICATING A MICROELECTROMECHANICAL SYSTEM  
(MEMS) DEVICE USING A PRE-PATTERNEDE BRIDGE

ABSTRACT OF THE INVENTION

A method for fabricating MEMS structures includes etching a recess in either an upper surface of a substrate that is bonded to a wafer that ultimately forms the MEMS structure, or to the lower surface of the wafer that is bonded to the substrate. Accordingly, once the etching processes of the wafer are completed, the recess facilitates the release of an internal movable structure within the fabricated MEMS structure without the use of a separate sacrificial material. Furthermore, a bridge, which is preferably insulating, is pre-etched before the wafer is attached to the substrate.

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